

MT18Ex

- Micro Thin為附18 μ m載體銅箔的超薄銅箔。
Micro Thin is ultra thin foil with 18 μ m carrier foil.
- 最適用於線寬/線距(L/S)=25/25~40/40之應用。
Usable for fine pitch pattern L/S=25/25 – 40/40 formation.
- 與MT18SD-H相比較, 其更低的粗糙度更適用於極細線路之應用。
Lower profile compare with MT18SD-H, more suitable for very fine pattern.

用途/Application

- IC封裝載板
/Semiconductor Package

構成/Composition



生產地點/Production Site

- 日本 / Japan

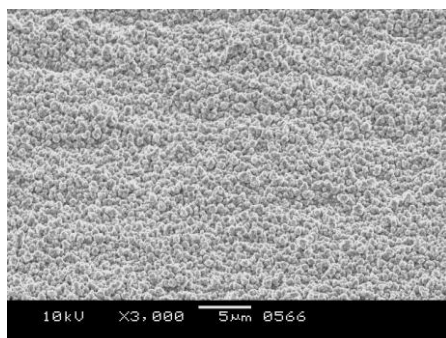
代表性特性數據/Representative

	μ m	Laminate side Rz(μ m)	Tensile Strength (N/mm ²)	Elongation (%)	Peel Strength (kg/cm) ⁴ @FR-4
MT18Ex	2	2	—	—	1.1
	3	2	—	—	1.1
	5	2	—	—	1.1

※上述表列為代表性數據非保証值
This is representative data, not guarantee.

※Peel Strength為增鍍到35 μ m厚度之後的測試值
Evaluated after plated up to 35 μ m.

處理面/Laminate side



阻劑面/ resist side

